

SOJ, TSOP, FP-BGA
Commercial Temp
Industrial Temp

256K x 16

4Mb Asynchronous SRAM

8, 10, 12, 15ns
3.3V V_{DD}
Center V_{DD} & V_{SS}

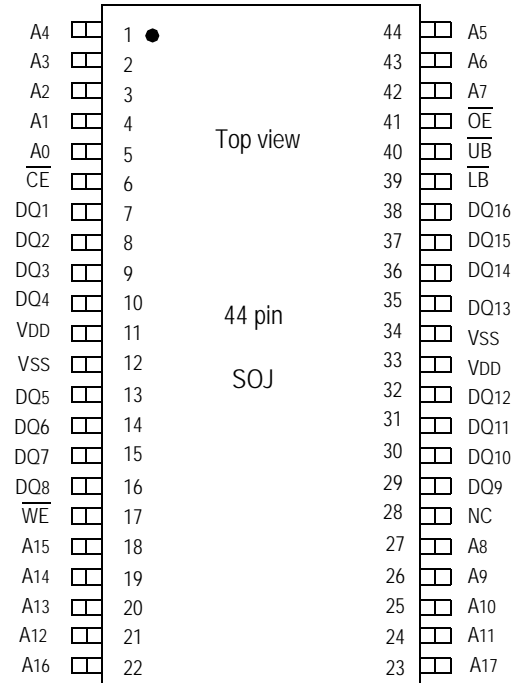
Features

- Fast access time: 8, 10, 12, 15ns
- CMOS low power operation: 170/145/130/110 mA at min.cycle time.
- Single 3.3V ± 0.3V power supply
- All inputs and outputs are TTL compatible
- Byte control
- Fully static operation
- Industrial Temperature Option: -40° to 85°C
- Package line up
 - J: 400mil, 44 pin SOJ package
 - TP: 400mil, 44 pin TSOP Type II package
 - U: 7.20mm x 11.65mm Fine Pitch Ball Grid Array package

Description

The GS74116 is a high speed CMOS static RAM organized as 262,144-words by 16-bits. Static design eliminates the need for external clocks or timing strobes. Operating on a single 3.3V power supply and all inputs and outputs are TTL compatible. The GS74116 is available in a 7.2x11.65 mm Fine Pitch BGA package, 400 mil SOJ and 400 mil TSOP Type-II packages.

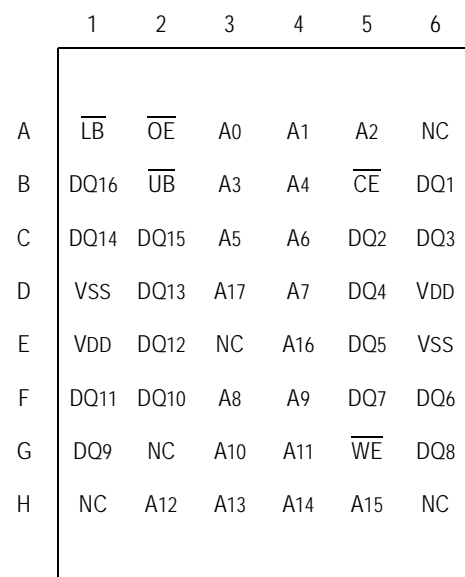
SOJ 256K x 16 Pin Configuration



Pin Descriptions

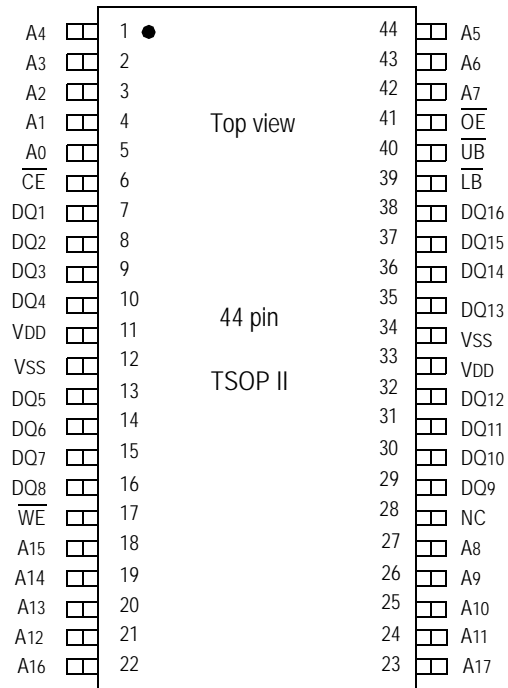
Symbol	Description
A ₀ to A ₁₇	Address input
DQ ₁ to DQ ₁₆	Data input/output
\overline{CE}	Chip enable input
\overline{LB}	Lower byte enable input (DQ ₁ to DQ ₈)
\overline{UB}	Upper byte enable input (DQ ₉ to DQ ₁₆)
\overline{WE}	Write enable input
\overline{OE}	Output enable input
V _{DD}	+3.3V power supply
V _{SS}	Ground
NC	No connect

Fine Pitch BGA 256K x 16 Bump Configuration

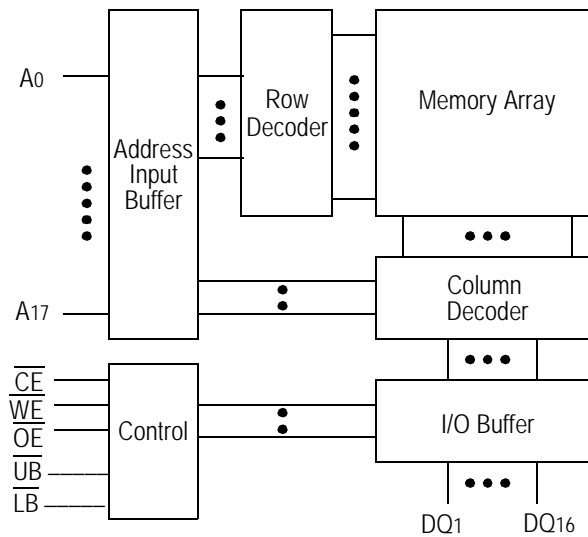


7.2x11.65mm 0.75mm Bump Pitch
Top View

TSOP-II 256K x 16 Pin Configuration



Block Diagram



Truth Table

\overline{CE}	\overline{OE}	\overline{WE}	\overline{LB}	\overline{UB}	DQ1 to DQ8	DQ9 to DQ16	VDD Current
H	X	X	X	X	Not Selected	Not Selected	ISB1, ISB2
L	L	H	L	L	Read	Read	I _{DD}
			L	H	Read	High Z	
			H	L	High Z	Read	
L	X	L	L	L	Write	Write	
			L	H	Write	Not Write, High Z	
			H	L	Not Write, High Z	Write	
L	H	H	X	X	High Z	High Z	
L	X	X	H	H	High Z	High Z	

Note: X: "H" or "L"

Absolute Maximum Ratings

Parameter	Symbol	Rating	Unit
Supply Voltage	V _{DD}	-0.5 to +4.6	V
Input Voltage	V _{IN}	-0.5 to V _{DD} +0.5 (≤ 4.6V max.)	V
Output Voltage	V _{OUT}	-0.5 to V _{DD} +0.5 (≤ 4.6V max.)	V
Allowable power dissipation	PD	0.7	W
Storage temperature	T _{STG}	-55 to 150	°C

Note:

Permanent device damage may occur if Absolute Maximum Ratings are exceeded. Functional operation shall be restricted to Recommended Operating Conditions. Exposure to higher than recommended voltages for extended periods of time could affect device reliability.

Recommended Operating Conditions

Parameter	Symbol	Min	Typ	Max	Unit
Supply Voltage for -10/12/15	V _{DD}	3.0	3.3	3.6	V
Supply Voltage for -8	V _{DD}	3.135	3.3	3.6	V
Input High Voltage	V _{IH}	2.0	-	V _{DD} +0.3	V
Input Low Voltage	V _{IL}	-0.3	-	0.8	V
Ambient Temperature, Commercial Range	T _{Ac}	0	-	70	°C
Ambient Temperature, Industrial Range	T _{AI}	-40	-	85	°C

Note:

1. Input overshoot voltage should be less than V_{DD}+2V and not exceed 20ns.
2. Input undershoot voltage should be greater than -2V and not exceed 20ns.

Capacitance

Parameter	Symbol	Test Condition	Max	Unit
Input Capacitance	C _{IN}	V _{IN} =0V	5	pF
Output Capacitance	C _{OUT}	V _{OUT} =0V	7	pF

Notes:

1. Tested at T_A=25°C, f=1MHz
2. These parameters are sampled and are not 100% tested

DC I/O Pin Characteristics

Parameter	Symbol	Test Conditions	Min	Max
Input Leakage Current	I _{IL}	V _{IN} = 0 to V _{DD}	-1uA	1uA
Output Leakage Current	I _{LO}	Output High Z V _{OUT} = 0 to V _{DD}	-1uA	1uA
Output High Voltage	V _{OH}	I _{OH} = - 4mA	2.4	
Output Low Voltage	V _{OL}	I _{LO} = + 4mA		0.4V

Power Supply Currents

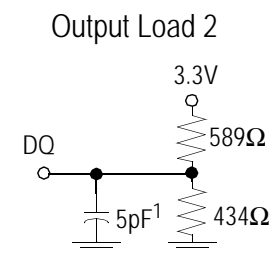
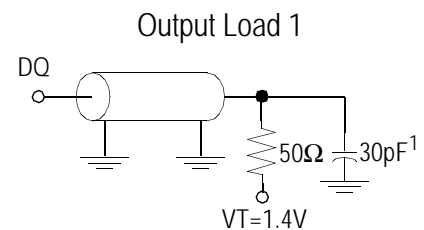
Parameter	Symbol	Test Conditions	0 to 70°C				-40 to 85°C		
			8ns	10ns	12ns	15ns	10ns	12ns	15ns
Operating Supply Current	I _{DD}	$\overline{CE} \leq V_{IL}$ All other inputs $\geq V_{IH}$ or $\leq V_{IL}$ Min. cycle time I _{OUT} = 0 mA	170mA	145mA	130mA	110mA	155mA	140mA	120mA
Standby Current	I _{SB1}	$\overline{CE} \geq V_{IH}$ All other inputs $\geq V_{IH}$ or $\leq V_{IL}$ Min. cycle time	70mA	65mA	60mA	55mA	75mA	70mA	65mA
Standby Current	I _{SB2}	$\overline{CE} \geq V_{DD} - 0.2V$ All other inputs $\geq V_{DD} - 0.2V$ or $\leq 0.2V$	30mA				40mA		

AC Test Conditions

Parameter	Conditions
Input high level	V _{IH} =2.4V
Input low level	V _{IL} =0.4V
Input rise time	t _r =1V/ns
Input fall time	t _f =1V/ns
Input reference level	1.4V
Output reference level	1.4V
Output load	Fig. 1 & 2

Note:

1. Include scope and jig capacitance.
2. Test conditions as specified with output loading as shown in Fig. 1 unless otherwise noted
3. Output load 2 for t_{LZ}, t_{HZ}, t_{OLZ} and t_{OHZ}.



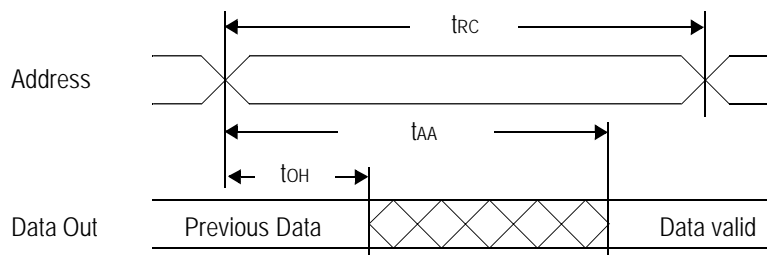
AC Characteristics

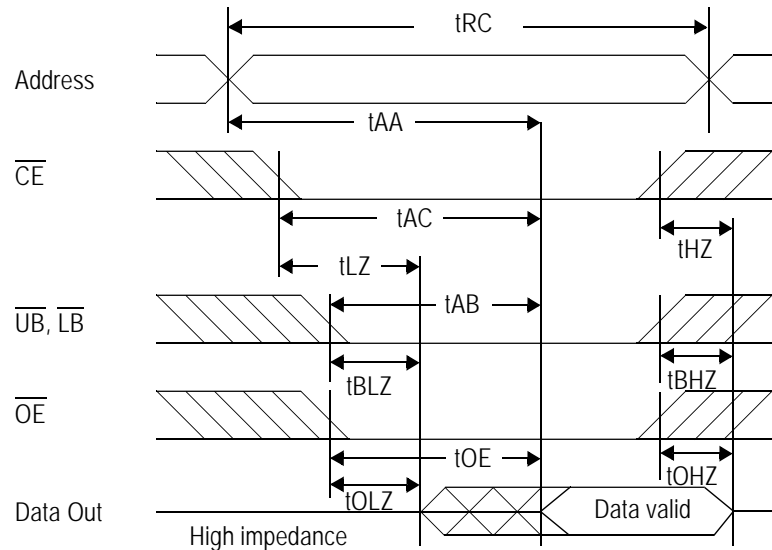
Read Cycle

Parameter	Symbol	-8		-10		-12		-15		Unit
		Min	Max	Min	Max	Min	Max	Min	Max	
Read cycle time	t_{RC}	8	---	10	---	12	---	15	---	ns
Address access time	t_{AA}	---	8	---	10	---	12	---	15	ns
Chip enable access time (\overline{CE})	t_{AC}	---	8	---	10	---	12	---	15	ns
Byte enable access time (\overline{UB} , \overline{LB})	t_{AB}	---	3.5	---	4	---	5	---	6	ns
Output enable to output valid (\overline{OE})	t_{OE}	---	3.5	---	4	---	5	---	6	ns
Output hold from address change	t_{OH}	3	---	3	---	3	---	3	---	ns
Chip enable to output in low Z (\overline{CE})	t_{LZ}^*	3	---	3	---	3	---	3	---	ns
Output enable to output in low Z (\overline{OE})	t_{OLZ}^*	0	---	0	---	0	---	0	---	ns
Byte enable to output in low Z (\overline{UB} , \overline{LB})	t_{BLZ}^*	0	---	0	---	0	---	0	---	ns
Chip disable to output in High Z (\overline{CE})	t_{HZ}^*	---	4	---	5	---	6	---	7	ns
Output disable to output in High Z (\overline{OE})	t_{OHZ}^*	---	3.5	---	4	---	5	---	6	ns
Byte disable to output in High Z (\overline{UB} , \overline{LB})	t_{BHZ}^*	---	3.5	---	4	---	5	---	6	ns

* These parameters are sampled and are not 100% tested

Read Cycle 1: $\overline{CE} = \overline{OE} = V_{IL}$, $\overline{WE} = V_{IH}$, \overline{UB} and, or $\overline{LB} = V_{IL}$

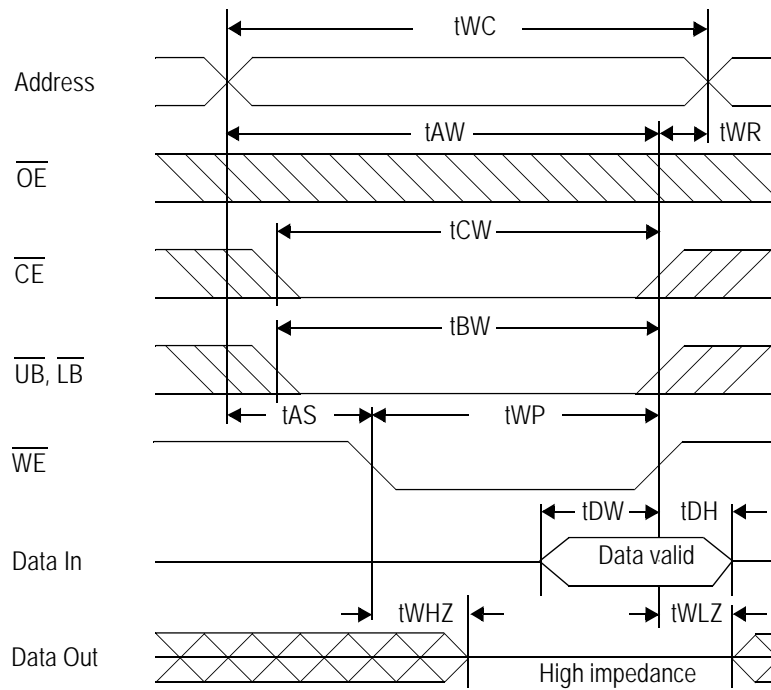
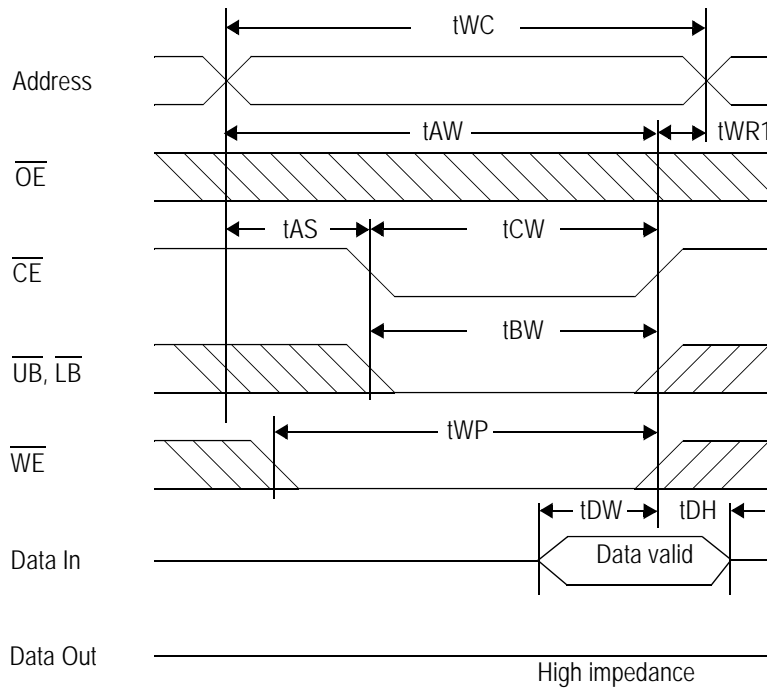


Read Cycle 2: $\overline{WE} = V_{IH}$


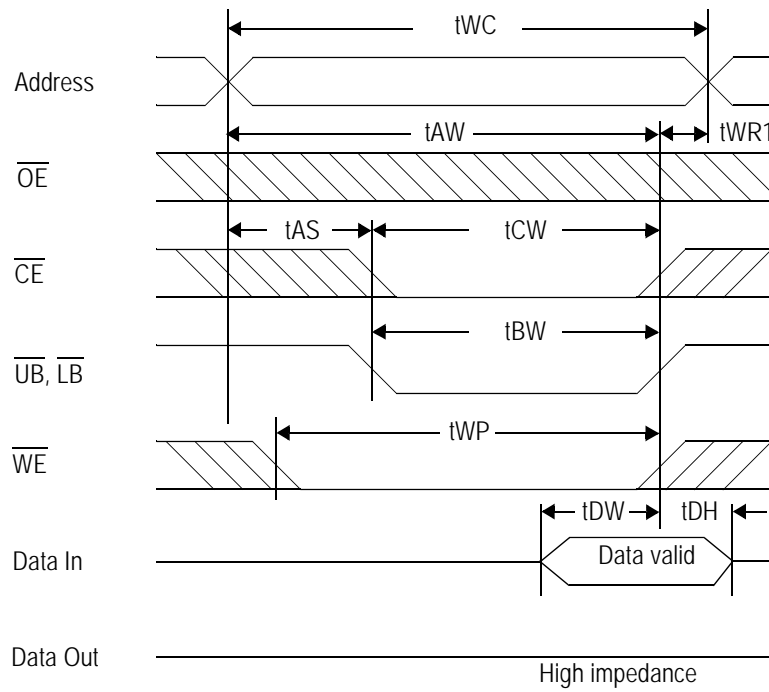
Write Cycle

Parameter	Symbol	-8		-10		-12		-15		Unit
		Min	Max	Min	Max	Min	Max	Min	Max	
Write cycle time	t_{WC}	8	---	10	---	12	---	15	---	ns
Address valid to end of write	t_{AW}	5.5	---	7	---	8	---	10	---	ns
Chip enable to end of write	t_{CW}	5.5	---	7	---	8	---	10	---	ns
Byte enable to end of write	t_{BW}	5.5	---	7	---	8	---	10	---	ns
Data set up time	t_{DW}	4	---	5	---	6	---	7	---	ns
Data hold time	t_{DH}	0	---	0	---	0	---	0	---	ns
Write pulse width	t_{WP}	5.5	---	7	---	8	---	10	---	ns
Address set up time	t_{AS}	0	---	0	---	0	---	0	---	ns
Write recovery time (\overline{WE})	t_{WR}	0	---	0	---	0	---	0	---	ns
Write recovery time (\overline{CE})	t_{WR1}	0	---	0	---	0	---	0	---	ns
Output Low Z from end of write	t_{WLZ}^*	3	---	3	---	3	---	3	---	ns
Write to output in High Z	t_{WHZ}^*	---	3.5	---	4	---	5	---	6	ns

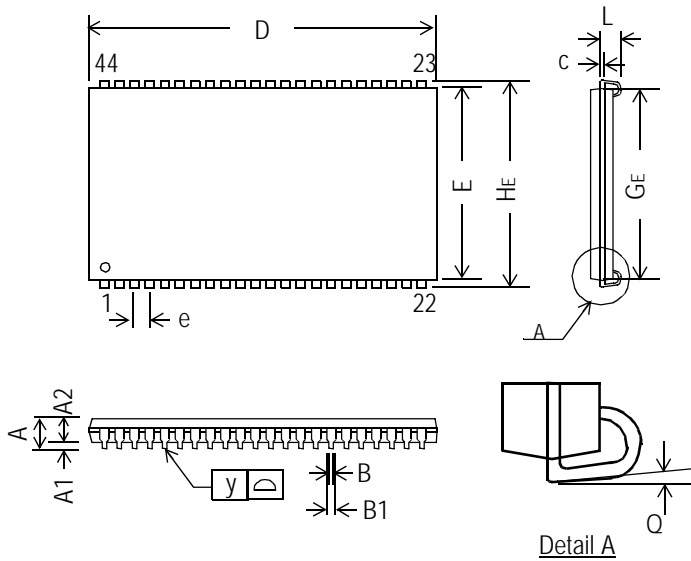
* These parameters are sampled and are not 100% tested

Write Cycle 1: \overline{WE} control

 Write Cycle 2: \overline{CE} control


Write Cycle 3: \overline{UB} , \overline{LB} control



44 Pin, 400 mil SOJ

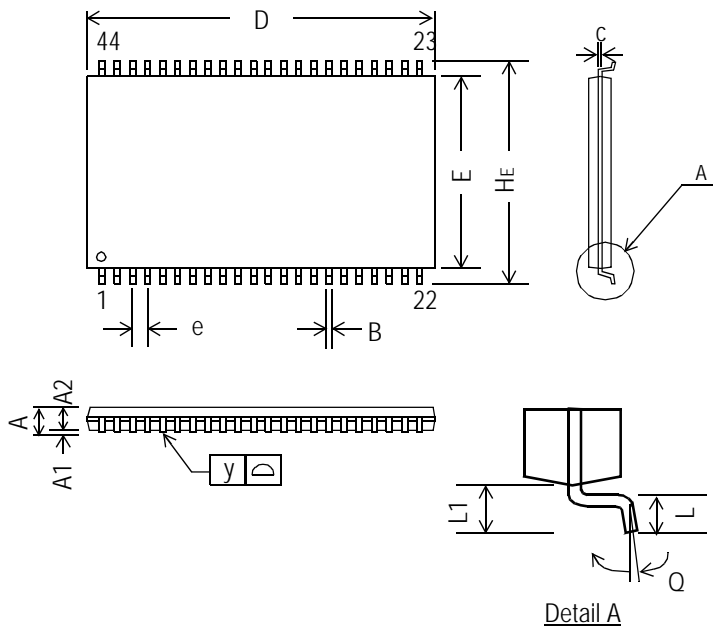


Symbol	Dimension in inch			Dimension in mm		
	min	nom	max	min	nom	max
A	-	-	0.148	-	-	3.759
A1	0.025	-	-	0.635	-	-
A2	0.105	0.110	0.115	2.667	2.794	2.921
B	-	0.018	-	-	0.457	-
B1	0.026	0.028	0.032	0.660	0.711	0.813
c	-	0.008	-	-	0.203	-
D	1.120	1.125	1.130	28.44	28.58	28.70
E	0.395	0.400	0.405	10.033	10.160	10.287
e	-	0.05	-	-	1.27	-
HE	0.435	0.440	0.445	11.049	11.176	11.303
GE	0.360	0.370	0.380	9.144	9.398	9.652
L	0.082	0.087	0.106	2.083	2.210	2.70
y	-	-	0.004	-	-	0.102
Q	0°	-	7°	0°	-	7°

Note:

1. Dimension D & E do not include interlead flash
2. Dimension B1 does not include dambar protrusion / intrusion

44 Pin, 400 mil TSOP-II

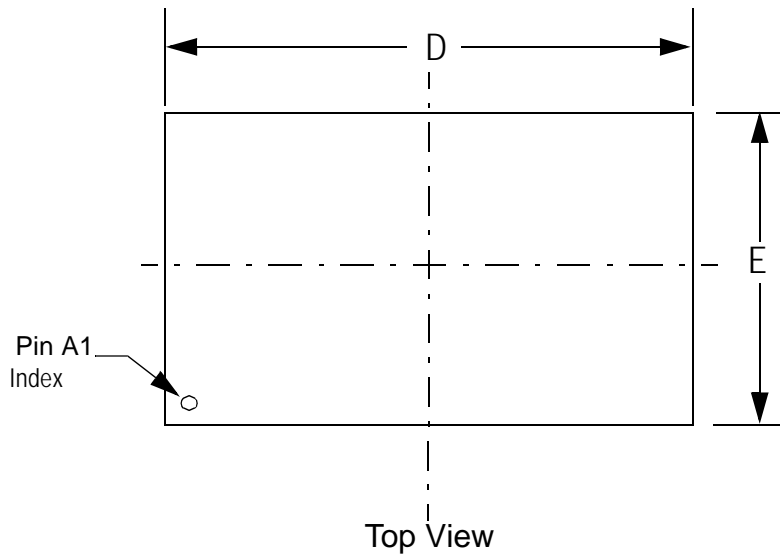


Symbol	Dimension in inch			Dimension in mm		
	min	nom	max	min	nom	max
A	-	-	0.047	-	-	1.20
A1	0.002	-	-	0.05	-	-
A2	0.037	0.039	0.041	0.95	1.00	1.05
B	0.01	0.014	0.018	0.25	0.35	0.45
c	-	0.006	-	-	0.15	-
D	0.721	0.725	0.729	18.31	18.41	18.51
E	0.396	0.400	0.404	10.06	10.16	10.26
e	-	0.031	-	-	0.80	-
HE	0.455	0.463	0.471	11.56	11.76	11.96
L	0.016	0.020	0.024	0.40	0.50	0.60
L1	-	0.031	-	-	0.80	-
y	-	-	0.004	-	-	0.10
Q	0°	-	5°	0°	-	5°

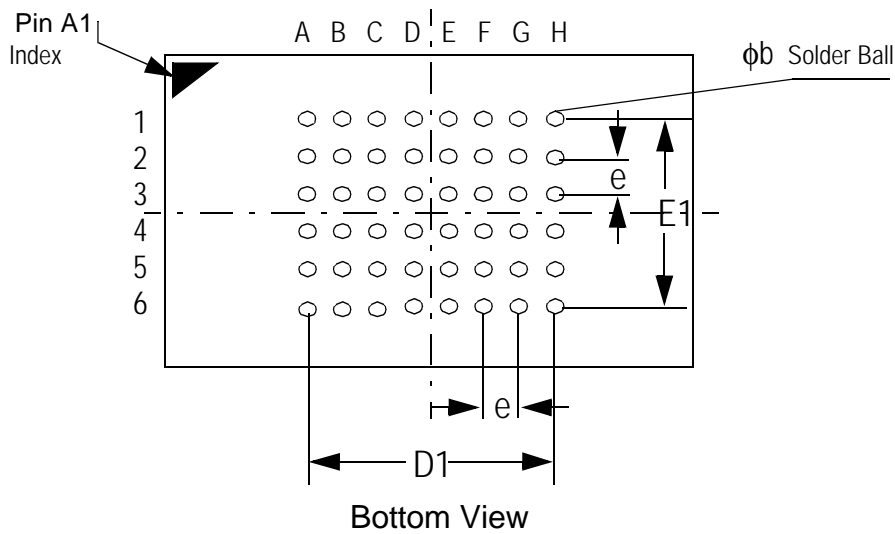
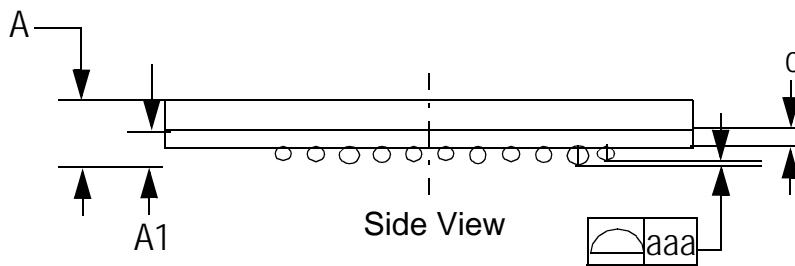
Note:

1. Dimension D & E do not include interlead flash
2. Dimension B does not include dambar protrusion / intrusion
3. Controlling dimension: mm

7.2mmx11.65mm FP-BGA



Symbol	Unit: mm
A	1.10±0.10
A1	0.22±0.05
φb	φ0.35
c	0.36(TYP)
D	11.65±0.10
D1	5.25
E	7.20±0.10
E1	3.75
e	0.75(TYP)
aaa	0.10



Ordering Information

Part Number *	Package	Access Time	Temp. Range	Status
GS74116TP-8	400 mil TSOP-II	8 ns	Commercial	
GS74116TP-10	400 mil TSOP-II	10 ns	Commercial	
GS74116TP-12	400 mil TSOP-II	12 ns	Commercial	
GS74116TP-15	400 mil TSOP-II	15 ns	Commercial	
GS74116TP-8I	400 mil TSOP-II	8 ns	Industrial	
GS74116TP-10I	400 mil TSOP-II	10 ns	Industrial	
GS74116TP-12I	400 mil TSOP-II	12 ns	Industrial	
GS74116TP-15I	400 mil TSOP-II	15 ns	Industrial	
GS74116J-8	400 mil SOJ	8 ns	Commercial	
GS74116J-10	400 mil SOJ	10 ns	Commercial	
GS74116J-12	400 mil SOJ	12 ns	Commercial	
GS74116J-15	400 mil SOJ	15 ns	Commercial	
GS74116J-8I	400 mil SOJ	8 ns	Industrial	
GS74116J-10I	400 mil SOJ	10 ns	Industrial	
GS74116J-12I	400 mil SOJ	12 ns	Industrial	
GS74116J-15I	400 mil SOJ	15 ns	Industrial	
GS74116U-8	Fine Pitch BGA	8 ns	Commercial	
GS74116U-10	Fine Pitch BGA	10 ns	Commercial	
GS74116U-12	Fine Pitch BGA	12 ns	Commercial	
GS74116U-15	Fine Pitch BGA	15 ns	Commercial	
GS74116U-8I	Fine Pitch BGA	8 ns	Industrial	
GS74116U-10I	Fine Pitch BGA	10 ns	Industrial	
GS74116U-12I	Fine Pitch BGA	12 ns	Industrial	
GS74116U-15I	Fine Pitch BGA	15 ns	Industrial	

* Customers requiring delivery in Tape and Reel should add the character "T" to the end of the part number. For example: GS74116TP-10T

Revision History

Rev. Code: Old; New	Types of Changes Format or Content	Page #/Revisions/Reason
Rev1.03c 3/1999; 1.04d 6/1999	Format/Typos	Document/Changed format of subscripts on pins to small caps.
	Content	13/Changed Tape and Reel Note at end of Ordering info./Enhancement
1.04d 6/1999; 2.00 8/1999	Format/Typos	None
	Content	1. Added Fine Pitch BGA package to datasheet. 2. 10/Added Dimension "D" to SOJ package diagram/Was missing 3. 11/Added Dimension "D" to TSOP package diagram/Was missing
GS741Rev2.01KRev 21 2/2000L	Format/Content	1. GSI Logo 2.
GS74116 Rev2.01 2/2000L; Rev 2.02 3/2000N	Content	1. Changed Pin A17 from 3E to 3D.